

AN 1999:199668 HCAPLUS
 DN 130:199648
 TI Lead-free **solder** alloy
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 PA Senju Metal Industry Co., Ltd., Japan; Murata Mfg. Co., Ltd.
 SO Jpn. Kokai Tokkyo Koho, 4 pp.
 CODEN: JKXXAF

DT Patent
 LA Japanese

FAN.CNT 1

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PI	JP 11077368	A2	19990323	JP 1997-251405	19970902
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AB A Pb-free **solder** alloy is a **Sn** alloy contg. **Sb**
 1-10 (esp., 1-5), **Cu** 1-4, **Bi** 1-6, and In 1-5%. The
 alloy has a solidus temp. of .gtoreq.200.degree..